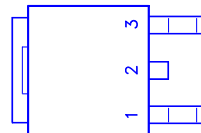
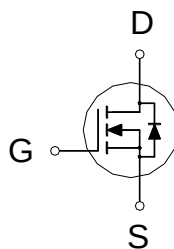


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
650V	400m Ω	11A



1. GATE
2. DRAIN
3. SOURCE


ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	650	V
Gate-Source Voltage		V_{GS}	± 30	V
Continuous Drain Current ²	$T_C = 25^\circ\text{C}$	I_D	11	A
	$T_C = 100^\circ\text{C}$		7	
Pulsed Drain Current ¹		I_{DM}	39	
Avalanche Current ³		I_{AS}	1.8	
Avalanche Energy ³		E_{AS}	120	mJ
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	83	W
	$T_C = 100^\circ\text{C}$		33	
Operating Junction & Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Ensure that the channel temperature does not exceed 150°C .

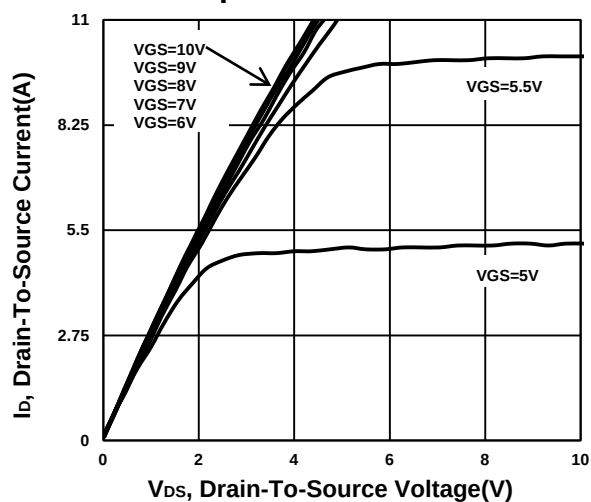
³ $V_{DD} = 50\text{V}$, $L = 75\text{mH}$, starting $T_J = 25^\circ\text{C}$.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

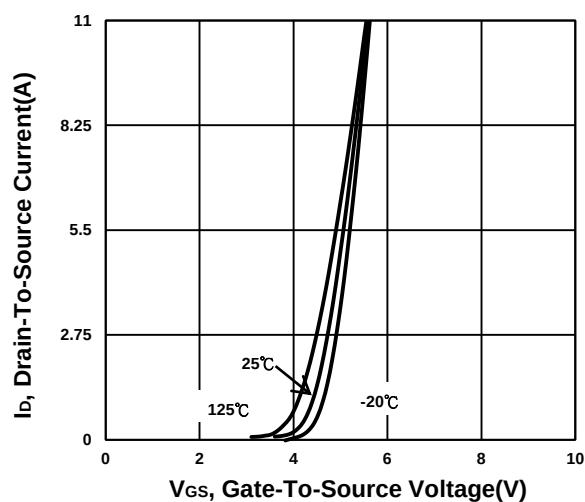
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	650			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3.3	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 650V, V_{GS} = 0V$			1	μA
		$V_{DS} = 520V, V_{GS} = 0V, T_J = 100^\circ C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 5.5A$		350	400	mΩ
Forward Transconductance ¹	g_{fs}	$V_{DS} = 15V, I_D = 5.5A$		9		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 100V, f = 250KHz$		767		pF
Output Capacitance	C_{oss}			42		
Reverse Transfer Capacitance	C_{rss}			5.2		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		19		Ω
Total Gate Charge ²	Q_g	$V_{DS} = 520V, V_{GS} = 10V, I_D = 5.5A$		24		nC
Gate-Source Charge ²	Q_{gs}			4.8		
Gate-Drain Charge ²	Q_{gd}			11		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 325V,$ $I_D \cong 5.5A, V_{GS} = 10V, R_{GEN} = 25\Omega$		22		nS
Rise Time ²	t_r			35		
Turn-Off Delay Time ²	$t_{d(off)}$			125		
Fall Time ²	t_f			45		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current	I_S				11	A
Forward Voltage ¹	V_{SD}	$I_F = 11A, V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 5.5A, di_F/dt = 100A/\mu s$		247		nS
Reverse Recovery Charge	Q_{rr}			2.6		uC

¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.

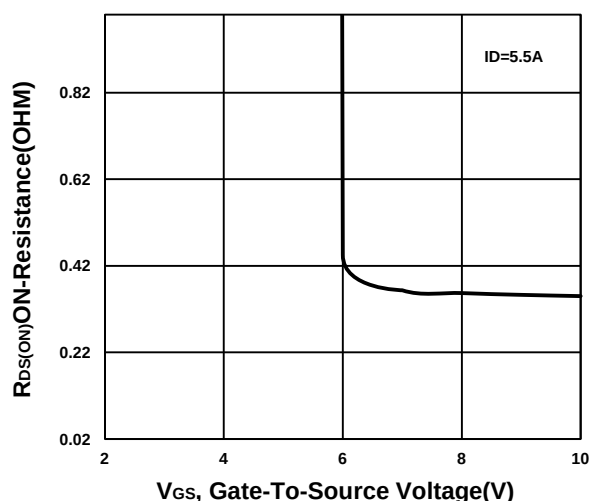
Output Characteristics



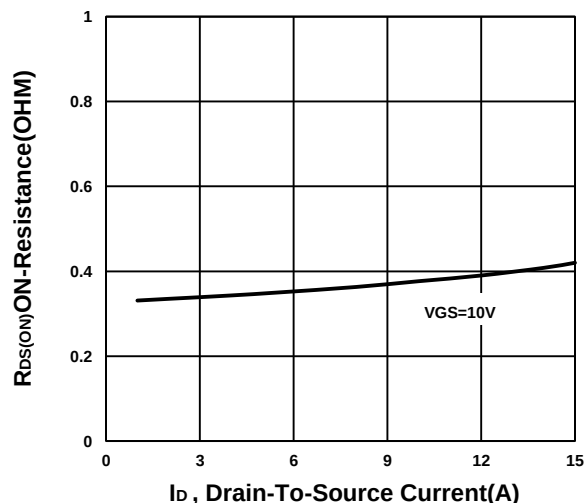
Transfer Characteristics



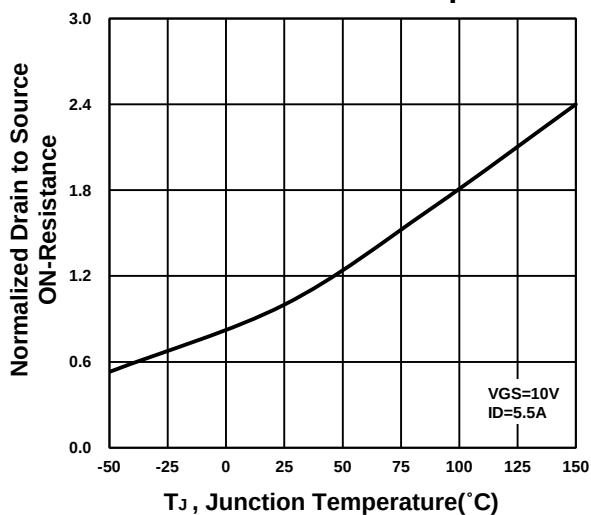
On-Resistance VS Gate-To-Source Voltage



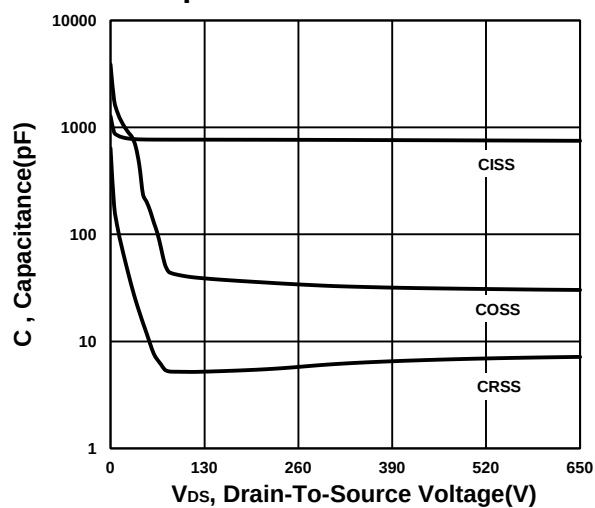
On-Resistance VS Drain Current



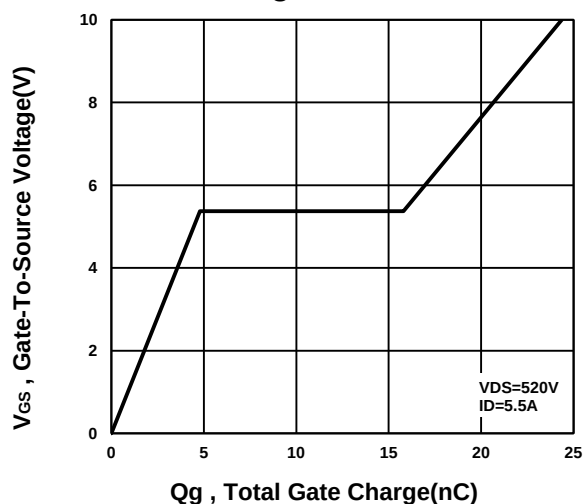
On-Resistance VS Temperature



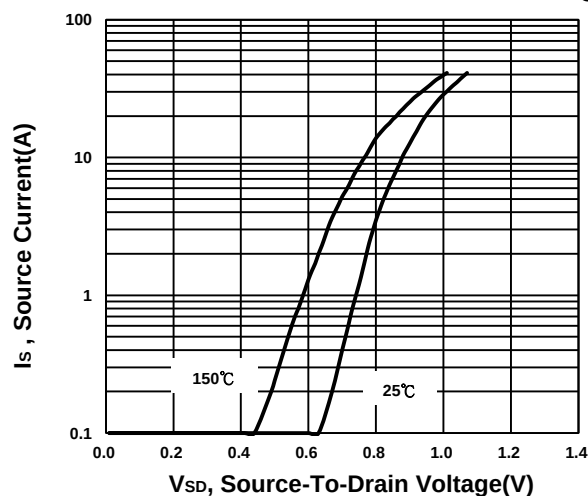
Capacitance Characteristic



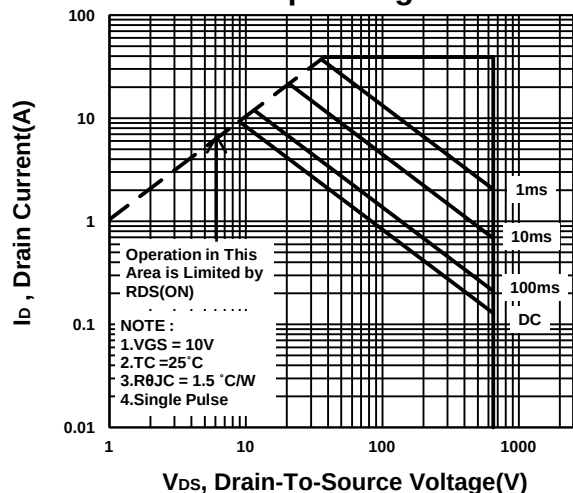
Gate charge Characteristics



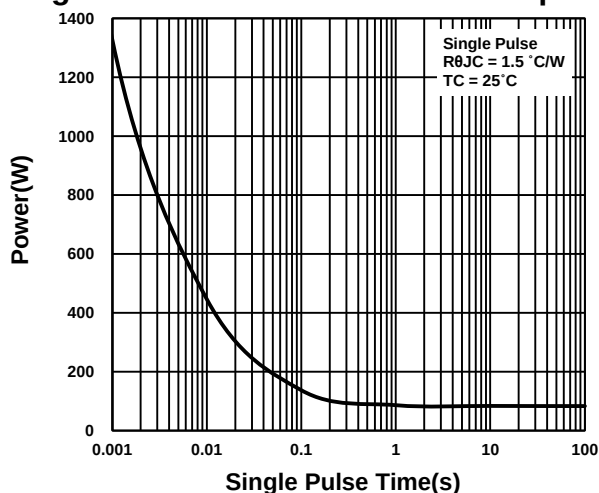
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

